NPN Silicon Power Darlington

High Voltage Autoprotected

The BU323Z is a planar, monolithic, high-voltage power Darlington with a built-in active zener clamping circuit. This device is specifically designed for unclamped, inductive applications such as Electronic Ignition, Switching Regulators and Motor Control, and exhibit the following main features:

- Integrated High-Voltage Active Clamp
- Tight Clamping Voltage Window (350 V to 450 V) Guaranteed Over the −40°C to +125°C Temperature Range
- Clamping Energy Capability 100% Tested in a Live Ignition Circuit
- High DC Current Gain/Low Saturation Voltages Specified Over Full Temperature Range
- Design Guarantees Operation in SOA at All Times
- Offered in Plastic SOT-93/TO-218 Type or TO-220 Packages
- Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating		Symbol	Max	Unit
Collector-Emitter Sustaining Voltage		V _{CEO}	350	Vdc
Collector-Emitter Voltage		V _{EBO}	6.0	Vdc
Collector Current	– Continuous – Peak	I _C I _{CM}	10 20	Adc
Base Current	ContinuousPeak	I _B I _{BM}	3.0 6.0	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C		P _D	150 1.0	W W/°C
Operating and Storage Junction Temperature Range		T _J , T _{stg}	-65 to +175	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.0	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	TL	260	°C

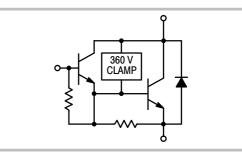
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

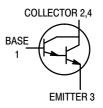


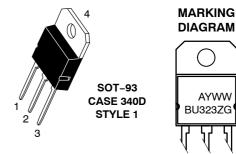
ON Semiconductor®

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10 AMPERE DARLINGTON AUTOPROTECTED 360 – 450 VOLTS CLAMP, 150 WATTS







A = Assembly Location

' = Year

WW = Work Week
G = Pb-Free Package
BU323Z = Device Code

ORDERING INFORMATION

Device	Package	Shipping
BU323Z	SOT-93	30 Units / Rail
BU323ZG	SOT-93 (Pb-Free)	30 Units / Rail

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS (1)	-		•	•	•	
Collector–Emitter Clamping Voltage ($I_C = 7.0 \text{ A}$) ($T_C = -40^{\circ}\text{C}$ to +125°C)		V_{CLAMP}	350	_	450	Vdc
Collector–Emitter Cutoff Current $(V_{CE} = 200 \text{ V}, I_B = 0)$		I _{CEO}	_	_	100	μAdc
Emitter–Base Leakage Current $(V_{EB} = 6.0 \text{ Vdc}, I_C = 0)$		I _{EBO}	_	_	50	mAdc
ON CHARACTERISTICS (1)			•	-	•	
Base–Emitter Saturation Voltage ($I_C = 8.0$ Adc, $I_B = 100$ mAdc) ($I_C = 10$ Adc, $I_B = 0.25$ Adc)		V _{BE(sat)}		_ _	2.2 2.5	Vdc
Collector–Emitter Saturation Voltage ($I_C = 7.0$ Adc, $I_B = 70$ mAdc) ($I_C = 8.0$ Adc, $I_B = 0.1$ Adc) ($I_C = 10$ Adc, $I_B = 0.25$ Adc)	(T _C = 125°C) (T _C = 125°C)	V _{CE(sat)}	_ _ _ _ _	_ _ _ _ _	1.6 1.8 1.8 2.1 1.7	Vdc
Base–Emitter On Voltage ($I_C = 5.0$ Adc, $V_{CE} = 2.0$ Vdc) ($I_C = 8.0$ Adc, $V_{CE} = 2.0$ Vdc)	$(T_C = -40^{\circ}C \text{ to } +125^{\circ}C)$	V _{BE(on)}	1.1 1.3	_ _	2.1 2.3	Vdc
Diode Forward Voltage Drop (I _F = 10 Adc)		V _F	_	_	2.5	Vdc
DC Current Gain $(I_C = 6.5 \text{ Adc}, V_{CE} = 1.5 \text{ Vdc})$ $(T_C = -40^{\circ}\text{C to } +125^{\circ}\text{C})$ $(I_C = 5.0 \text{ Adc}, V_{CE} = 4.6 \text{ Vdc})$		h _{FE}	150 500		 3400	_
DYNAMIC CHARACTERISTICS						
Current Gain Bandwidth (I _C = 0.2 Adc, V _{CE} = 10 Vdc, f = 1.0 MHz)	f _T	_	_	2.0	MHz	
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz)	C _{ob}	_	_	200	pF	
Input Capacitance (V _{EB} = 6.0 V)	C _{ib}	_	_	550	pF	
CLAMPING ENERGY (see notes)	-		•		•	
Repetitive Non–Destructive Energy Dissipated at turn–off: (I _C = 7.0 A, L = 8.0 mH, R_{BE} = 100 Ω) (see Figures 2 and 4)		W _{CLAMP}	200	_	_	mJ
SWITCHING CHARACTERISTICS: Inductive Load	I (L = 10 mH)					
Fall Time $(I_C = 6.5 \text{ A, } I_B)$	BE(GII) , BE(GII) ,		_	625	_	ns
Storage Time $V_{BE(off)} = 0, F$			_	10	30	μs
Cross-over Time V _{CC} = 14 V, V _Z = 300 V)		t _c		1.7		μs

⁽¹⁾ Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle = 2.0%.

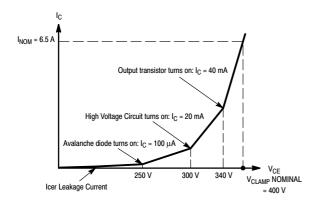


Figure 1. $I_C = f(V_{CE})$ Curve Shape

L INDUCTANCE MERCURY CONTACTS (8 mH) WETTED RELAY I_C CURRENT SOURCE V_{CE} MONITOR (V_{GATE}) R_{BE} = 100 Ω 0.1 Ω lc. I_B CURRENT NON MONITOR V_{BEoff} INDUCTIVE SOURCE I_{B2} SOURCE

Figure 2. Basic Energy Test Circuit

By design, the BU323Z has a built–in avalanche diode and a special high voltage driving circuit. During an auto–protect cycle, the transistor is turned on again as soon as a voltage, determined by the zener threshold and the network, is reached. This prevents the transistor from going into a Reverse Bias Operating limit condition. Therefore, the device will have an extended safe operating area and will always appear to be in "FBSOA." Because of the built–in zener and associated network, the $I_C = f(V_{CE})$ curve exhibits an unfamiliar shape compared to standard products as shown in Figure 1.

The bias parameters, V_{CLAMP} , I_{B1} , $V_{BE(off)}$, I_{B2} , I_{C} , and the inductance, are applied according to the Device Under Test (DUT) specifications. V_{CE} and I_{C} are monitored by the test system while making sure the load line remains within the limits as described in Figure 4.

Note: All BU323Z ignition devices are 100% energy tested, per the test circuit and criteria described in Figures 2 and 4, to the minimum guaranteed repetitive energy, as specified in the device parameter section. The device can sustain this energy on a repetitive basis without degrading any of the specified electrical characteristics of the devices. The units under test are kept functional during the complete test sequence for the test conditions described:

$$I_{C(peak)}$$
 = 7.0 A, $I_{C}H$ = 5.0 A, $I_{C}L$ = 100 mA, I_{B} = 100 mA, R_{BE} = 100 Ω , V_{gate} = 280 V, L = 8.0 mH

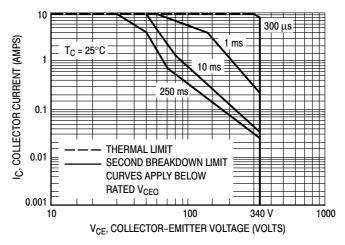
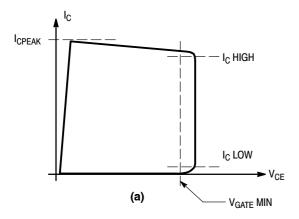
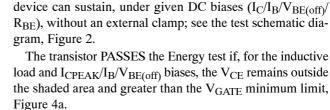
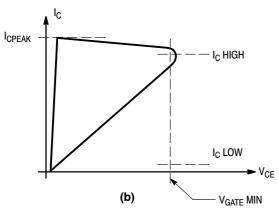


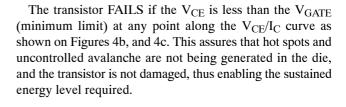
Figure 3. Forward Bias Safe Operating Area

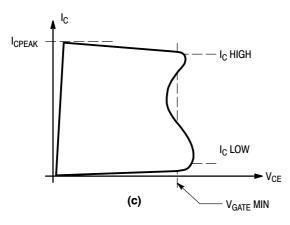


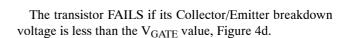


The shaded area represents the amount of energy the









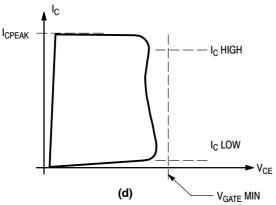


Figure 4. Energy Test Criteria for BU323Z

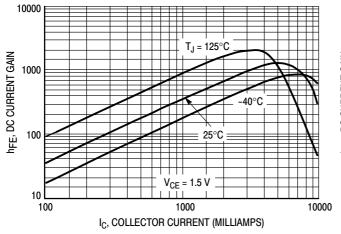


Figure 5. DC Current Gain

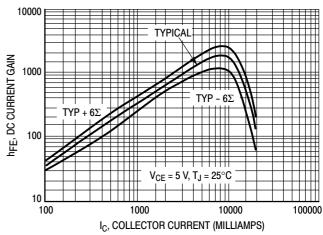


Figure 6. DC Current Gain

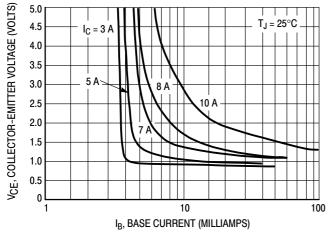


Figure 7. Collector Saturation Region

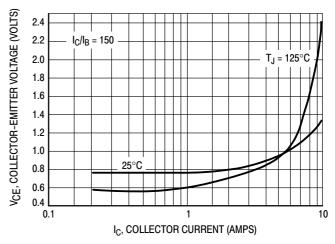


Figure 8. Collector-Emitter Saturation Voltage

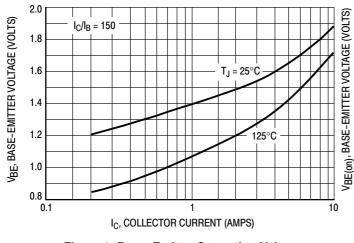


Figure 9. Base-Emitter Saturation Voltage

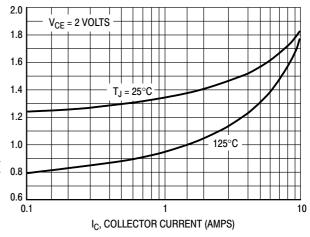
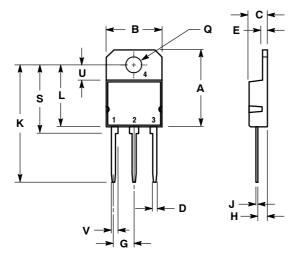


Figure 10. Base-Emitter "ON" Voltages

PACKAGE DIMENSIONS

SOT-93 (TO-218) **CASE 340D-02 ISSUE E**



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α		20.35		0.801	
В	14.70	15.20	0.579	0.598	
С	4.70	4.90	0.185	0.193	
D	1.10	1.30	0.043	0.051	
E	1.17	1.37	0.046	0.054	
G	5.40	5.55	0.213	0.219	
Н	2.00	3.00	0.079	0.118	
J	0.50	0.78	0.020	0.031	
K	31.00 REF		1.220 REF		
L		16.20		0.638	
Q	4.00	4.10	0.158	0.161	
S	17.80	18.20	0.701	0.717	
U	4.00 REF		0.157 REF		
V	1.75 REF		0.069		

STYLE 1:

PIN 1. BASE

- COLLECTOR
- **EMITTER** 3
- COLLECTOR

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